

Texas Instruments

FB PS LLC Test Report

HVPS SYSTEM AND APPLICATION TEAM

REVA

12/05/2014

1 General

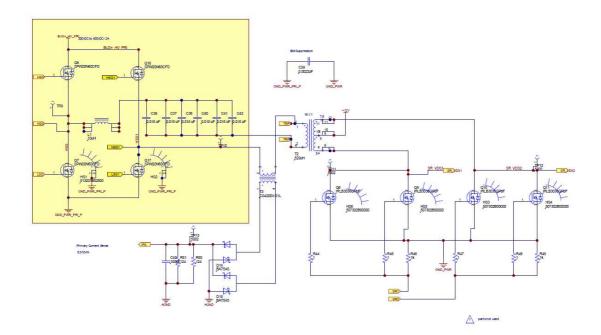
1.1 PURPOSE

Provide the detailed data for evaluating and verifying the FB-PS-LLC.

The FB-PS-LLC is a Full bridge Phase Shift LLC reference design realized by UCD3138. The topology is same as full bridge LLC. Full bridge LLC is always selected in high power level AC/DC application, and for output voltage in control under light load, PWM mode is always selected. But there is some disadvantages in PWM mode for LLC, like hard switch, high switch frequency and high power loss. The purpose of this reference design is to find a high efficiency method for LLC under light load. Select Phase shift mode replace of PWM mode under light load is a good method.

For testing applications, cooling airflow is required.

Block Diagram



Board Photo

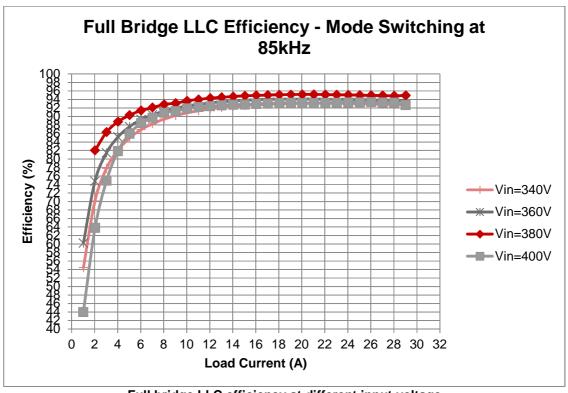


1.3 <u>TEST EQUIPMENTS</u>
Multi-meter:
AC Source: Chroma 61503 Load: Chroma 63202 Power Meter: WT210

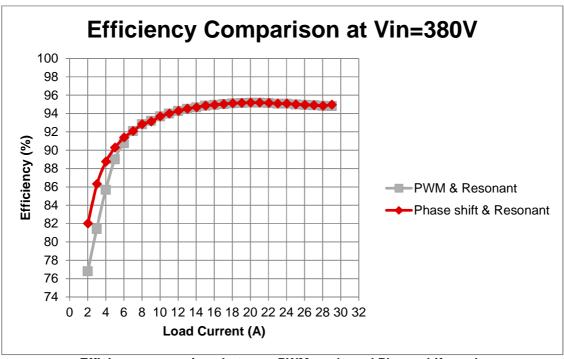
Ambient Temperature at 25DegC, with Fan cooling

2 INPUT & OUTPUT CHARACTERISTICS

2.1 **Efficiency comparison**

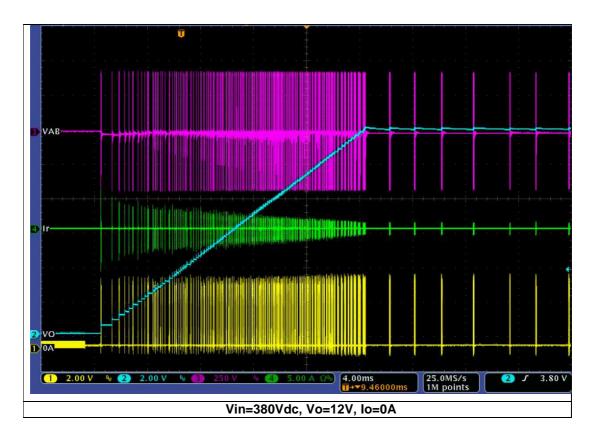


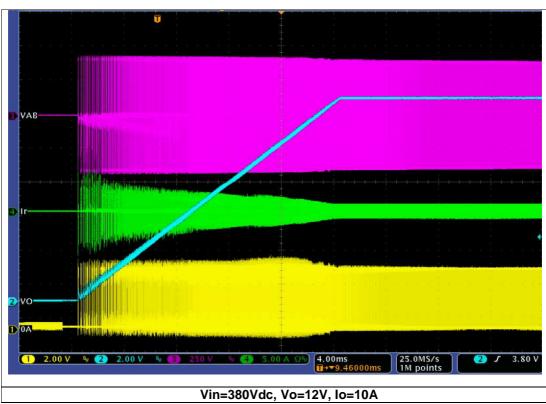
Full bridge LLC efficiency at different input voltage

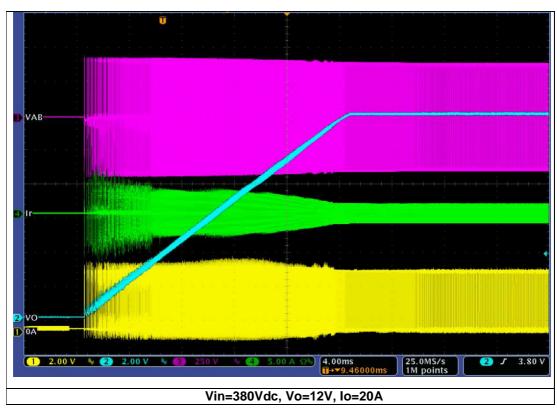


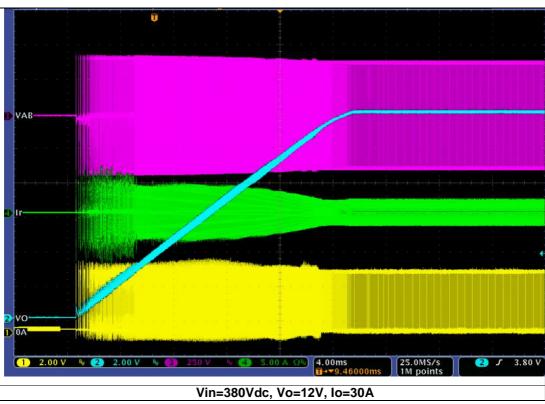
Efficiency comparison between PWM mode and Phase shift mode

2.2 The ramp up waveform







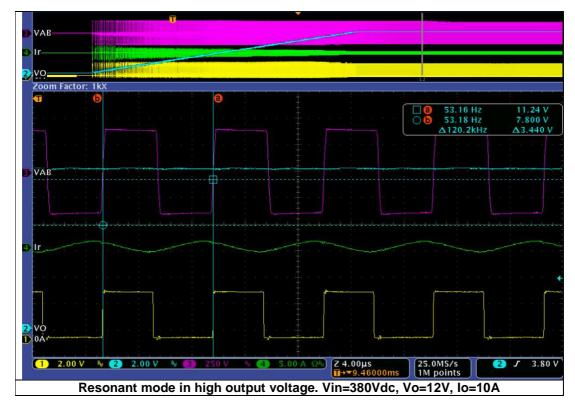




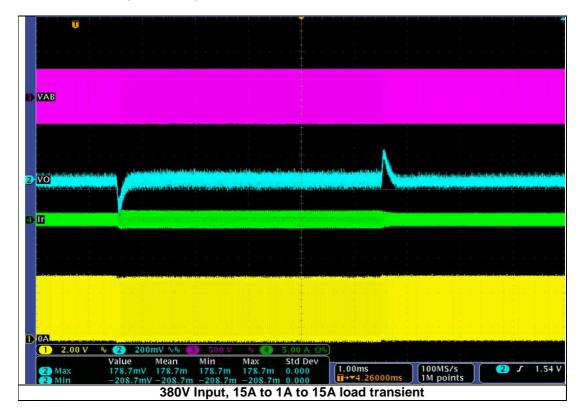
Phase shift mode in low output voltage. Vin=380Vdc, Vo=12V, Io=10A
Phase angle is very small, switch frequency is 150kHz (maximum switch frequency)

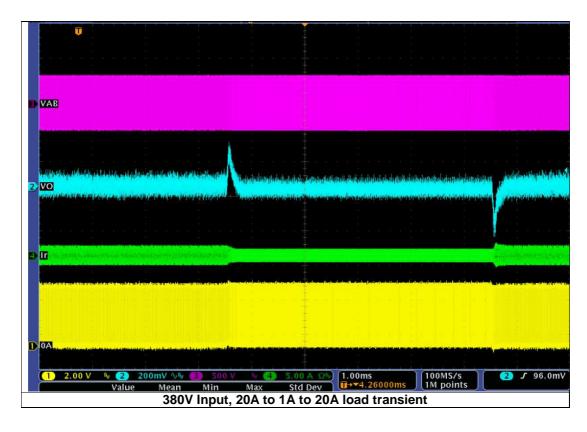


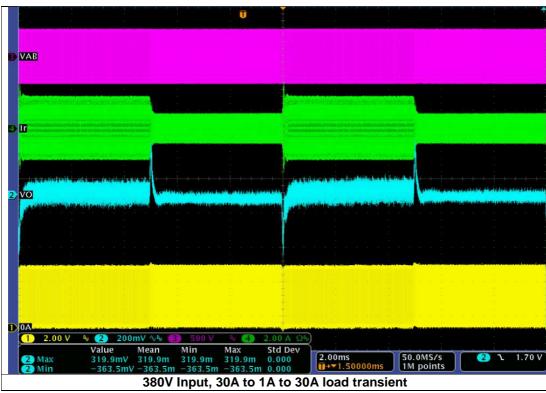
Phase shift mode in low output voltage. Vin=380Vdc, Vo=12V, Io=10A
Phase angle is increased, switch frequency is 150kHz (maximum switch frequency)

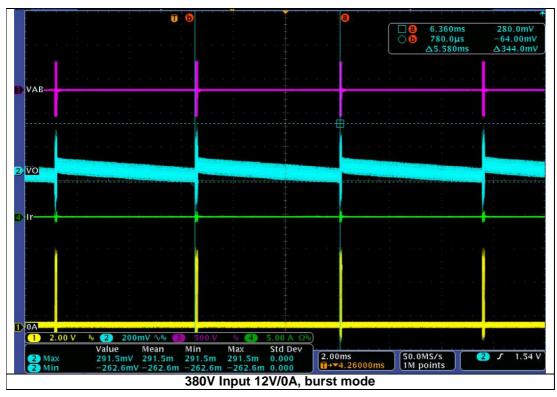


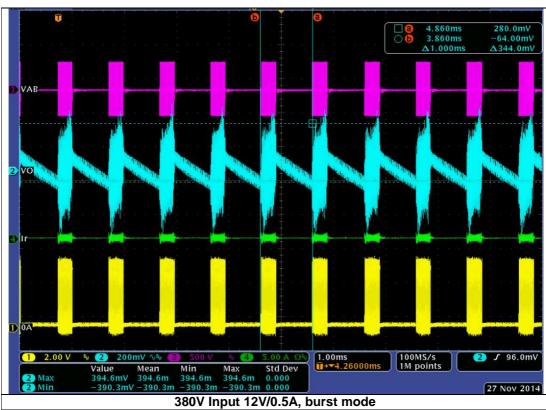
2.4 The load dynamic response Waveforms

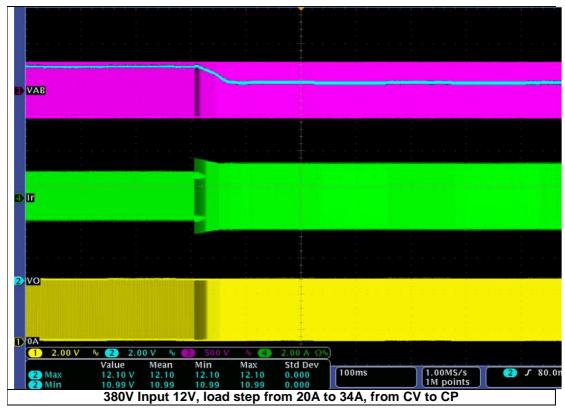


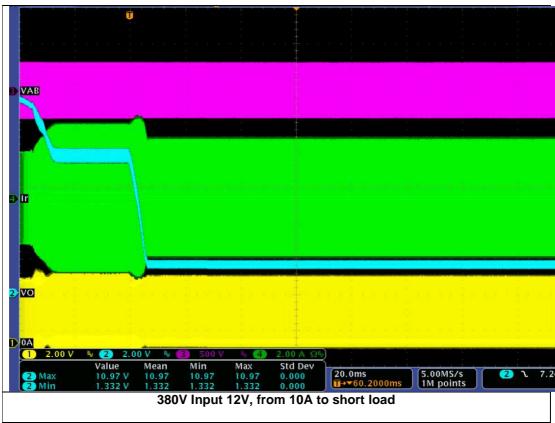














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